

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Youzhi E. Xu

Examiner: Not yet assigned

Serial No.: Not yet assigned

Art Unit: Not yet assigned

Filed: Herewith

For: IMPROVED HEAT TRANSFER THROUGH
COVALENT BONDING OF THERMAL
INTERFACE MATERIAL

Which is a Divisional of Application of:

Serial No: 10/062,255

Filed: January 31, 2002

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Applicant hereby requests consideration of the enclosed Information Disclosure Statement pursuant to 37 C.F.R §1.97(b). Attached are the PTO Forms 1449 and Forms 892 from the parent application filed on January 31, 2002 (Serial No. 10/062,255). This previous applications are relied upon for an earlier filing date under 35 U.S.C. §120.

Pursuant to C.F.R. §1.98(d), copies of the references are not being provided herewith since they were previously sent to the Patent and Trademark Office.

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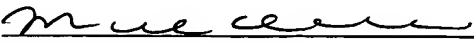
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Pursuant to 37 C.F.R. § 1.97, the submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made and is not to be construed as an admission that the information cited in this statement is material to patentability.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: 2/17, 2004


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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 1

Complete if Known

Application Number	10/062,255
Filing Date	January 31, 2002
First Named Inventor	Youzhi E. Xu
Group Art Unit	Not yet assigned
Examiner Name	Not yet assigned
Attorney Docket Number	42390P13563

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials ¹	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ²
UKA.		MIRNGH-JI LII ET AL.; Flip-Chip Technology on Organic Pin Grid Array Packages; Intel Technology Journal Q3, 2000; pp. 1-9. *	
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Notice of References Cited	Application/Control No. 10/062,255	Applicant(s)/Patent Under Reexamination XU, YOUZHI E.	
	Examiner Wesley A. Nicolas	Art Unit 1742	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-2003/0128521	07-2003	Matayabas et al.	361/705
	B	US-2002/0132896	09-2002	Nguyen	524/404
	C	US-5,403,783	04-1995	Nakanishi et al.	438/106
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